



## Material Content Data Sheet



<b>Sales Product Name</b>		ISO1I811T		<b>Issued</b>		19. July 2018		
<b>MA#</b>		MA001031790						
<b>Package</b>		PG-TSSOP-48-2		<b>Weight*</b>		203.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	9.257	4.56	4.56	45588	45588
leadframe	inorganic material	phosphorus	7723-14-0	0.019	0.01		94	
	non noble metal	zinc	7440-66-6	0.076	0.04		375	
	non noble metal	iron	7439-89-6	1.524	0.75		7507	
wire	non noble metal	copper	7440-50-8	61.896	30.48	31.28	304811	312787
	noble metal	gold	7440-57-5	0.451	0.22	0.22	2220	2220
	encapsulation	organic material	carbon black	1333-86-4	0.618	0.30		3041
encapsulation	plastics	epoxy resin	-	19.143	9.43		94273	
	inorganic material	silicondioxide	60676-86-0	103.744	51.09	60.82	510896	608210
leadfinish	non noble metal	tin	7440-31-5	2.496	1.23	1.23	12291	12291
plating	noble metal	silver	7440-22-4	0.774	0.38	0.38	3812	3812
glue	plastics	epoxy resin	-	0.766	0.38		3773	
	noble metal	silver	7440-22-4	2.298	1.13	1.51	11319	15092
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com